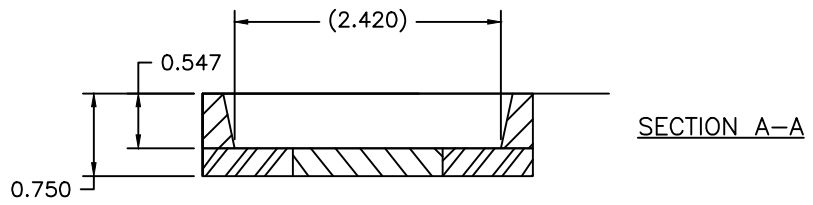
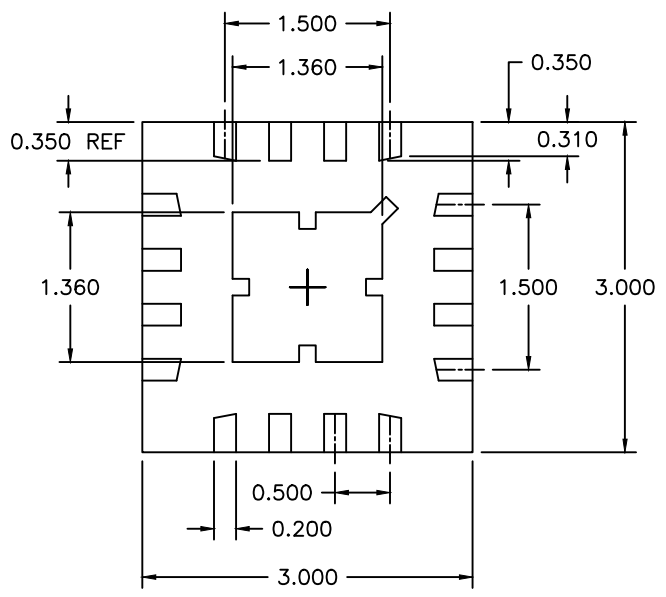
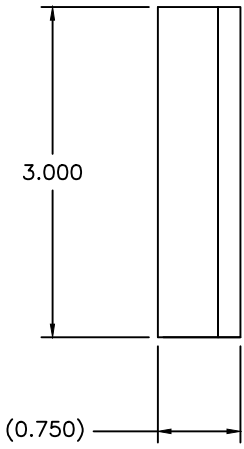
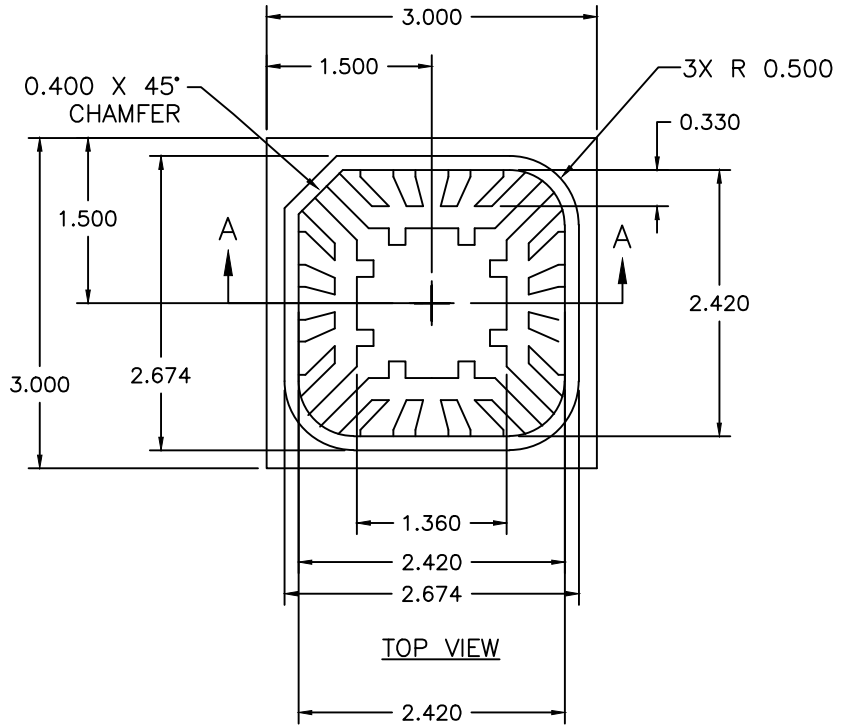


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SEMPAC REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
10786	10/30/06	INITIAL RELEASE	D.MORRIS



- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
 2. LEAD FRAME: COPPER, 194 FH.
 3. LEAD FINISH: FULL GOLD PLATE.
 4. FRAME THICKNESS: 0.2030 ±.0076.
 5. DIE PAD: 1.360mm X 1.360mm.
 6. JEDEC OUTLINE: MO-220 (VEED)

	THIRD ANGLE PROJECTION	DRAWN BY	C. CRUZ	DATE	10/30/06
	UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: X.XX ± 0.015 X.XXXX ± --- X.XXX ± 0.050 ANGLES: ± 1°	APP BY	P. FLASKERUD	DATE	10/30/06
DO NOT SCALE DRAWING		CUSTOMER	---		
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16 LEAD 3mm X 3mm
 MLP Open-Pak

SIZE	PART NO.	REV
A	MLP3X3-16-OP-01	4
SCALE	CAD FILE	SHEET
NONE	MLP3X3-16-OP-01-R4.DWG	1 OF 1

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